

**PAGE    REGULAR ISSUE PAPERS**

- 1867 A Diffuse Interface Model of Intermediate-Phase Growth Under the Influence of Electromigration  
*Peng Zhou and William C. Johnson*
- 1876 A Sharp Interface Model of Intermediate-Phase Growth Under the Influence of Electromigration  
*Peng Zhou, William C. Johnson, and Perry H. Leo*
- 1884 Characterization and Electrochemical Mechanism for Bromide-Containing Conductive Anodic Filament (CAF) Failure  
*Antonio Caputo, Laura J. Turbini, and Doug D. Perovic*
- 1895 Correlation Between Sn Grain Orientation and Corrosion in Sn-Ag-Cu Solder Interconnects  
*Tae-Kyu Lee, Bo Liu, Bite Zhou, Thomas Bieler, and Kuo-Chuan Liu*
- 1903 Effects of Cooling Rate and Composition on Mechanical Properties of Directionally Solidified  $Pb_{100-x}Sn_x$  Solders  
*E. Çadrlı, H. Kaya, and M. Şahin*
- 1912 Effects of Joining Sequence on the Interfacial Reactions and Substrate Dissolution Behaviors in Ni/Solder/Cu Joints  
*Chao Sheng Liu, Cheng En Ho, Cheng Sam Peng, and C. Robert Kao*
- 1921 Evaluation of Electrochemical Migration on Printed Circuit Boards with Lead-Free and Tin-Lead Solder  
*Xiaofei He, Michael H. Azarian, and Michael G. Pecht*
- 1937 Effect of Gold on the Corrosion Behavior of an Electroless Nickel/Immersion Gold Surface Finish  
*Q.V. Bui, N.D. Nam, J.W. Yoon, D.H. Choi, A. Kar, J.G. Kim, and S.B. Jung*
- 1943 Electromigration in a Sn-3 wt.%Ag-0.5 wt.%Cu-3 wt.%Bi Solder Stripe Between Two Cu Electrodes Under Current Stressing  
*Shang-Hua Lee and Chih-Ming Chen*
- 1950 Comparative Study of ENIG and ENEPIG as Surface Finishes for a Sn-Ag-Cu Solder Joint  
*Jeong-Won Yoon, Bo-In Noh, and Seung-Boo Jung*
- 1956 Reaction of Liquid Sn-Ag-Cu-Ce Solders with Solid Copper  
*J. Chrištel'ová, L. Rízeková Trnková, K. Pocisková Dimová, and M. Ožvold*
- 1962 Tin Whisker Growth on  $NdSn_3$  Powder  
*Hong-Chang Shi and Ai-Ping Xian*
- 1967 Impact of Isothermal Aging on Long-Term Reliability of Fine-Pitch Ball Grid Array Packages with Sn-Ag-Cu Solder Interconnects: Die Size Effects  
*Tae-Kyu Lee, Weidong Xie, Bite Zhou, Thomas Bieler, and Kuo-Chuan Liu*
- 1977 Effects of Solvent Type on Low-Temperature Sintering of Silver Oxide Paste to Form Electrically Conductive Silver Film  
*Inyoung Kim and Sangki Chun*
- 1984 Calculation of the Thermoelectric Power of Vanadium, Niobium, and Tantalum  
*Horst Brodowsky, Qiyuan Chen, Zhongliang Xiao, and Zhoulan Yin*
- 1990 Enhancement of the Stability of Ti and Ni Ohmic Contacts to 4H-SiC with a Stable Protective Coating for Harsh Environment Applications  
*Walter Daves, Andreas Krauss, Volker Häublein, Anton J. Bauer, and Lothar Frey*
- 1998 Effects of Thermal Annealing on the Formation of Buried  $\beta$ -SiC by Ion Implantation  
*P.R. Poudel, B. Rout, D.R. Diercks, J.A. Paramo, Y.M. Strzhemechny, and F.D. McDaniel*
- 2004 Synthesis and Characterization of  $SrFe_{11.2}Zn_{0.8}O_{19}$  Nanoparticles for Enhanced Microwave Absorption  
*Sachin Tyagi, Himanshu B. Baskey, Ramesh Chandra Agarwala, Vijaya Agarwala, and Trilok Chand Shami*

- 2015 Photoluminescence and Raman Spectroscopy of Polycrystalline ZnO Nanofibers Deposited by Electrospinning  
*Banani Sen, Michael Strosio, and Mitra Dutta*
- 2020 Electron Emission Properties of Surface-Conduction Electron Emitters With a PdO-C-PdO Multilayer Conductive Film Deposited by Magnetron Sputtering  
*W.B. Hu, Y.L. Sun, and S.L. Wu*
- 2027 Synthesis and Characterization of Polythiophene/Bi<sub>2</sub>Te<sub>3</sub> Nanocomposite Thermoelectric Material  
*W.Q. Ao, L. Wang, J.Q. Li, Fred Pan, and C.N. Wu*
- 2033 Hybrid Inorganic–Organic Heterojunction Solar Cell  
*Shaker Ebrahim, Moataz Soliman, and Tarek M. Abdel-Fattah*